

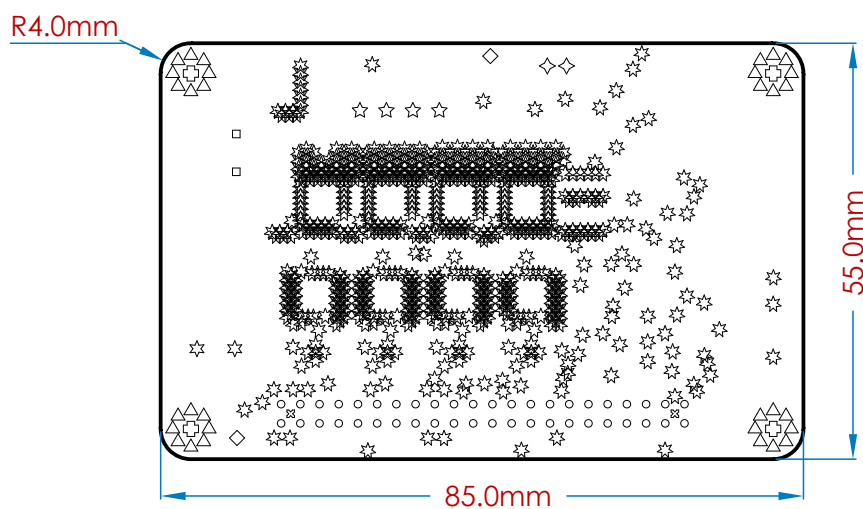
Layer Stack Legend

Material	Layer	Thickness	Gerber
	Top Paste		GTP
	Top Overlay		GTO
Surface Material	Top Soldermask	0.010mm	GTS
Copper	Top Layer	0.035mm	GTL
Prepreg		0.360mm	
Copper	Mid1	0.036mm	G1
Core		0.710mm	
Copper	Mid2	0.036mm	G2
Prepreg		0.360mm	
Copper	Bottom Layer	0.035mm	GBL
Surface Material	Bottom Soldermask	0.010mm	GBS
	Bottom Overlay		GBO
	Bottom Paste		GBP
Total thickness: 1.592mm			

Notes:

1. Use current revision of all standards.
2. Board is to be manufactured in accordance to IPC-6012 Class 2.
3. Laminate (core) and prepreg to be in accordance with IPC-4101/126
4. Board finish shall be ENIG
5. Soldermask colour shall be WHITE
6. Silkscreen colour shall be BLACK
7. All hole dimensions apply after plating
8. All copper dimensions apply after plating

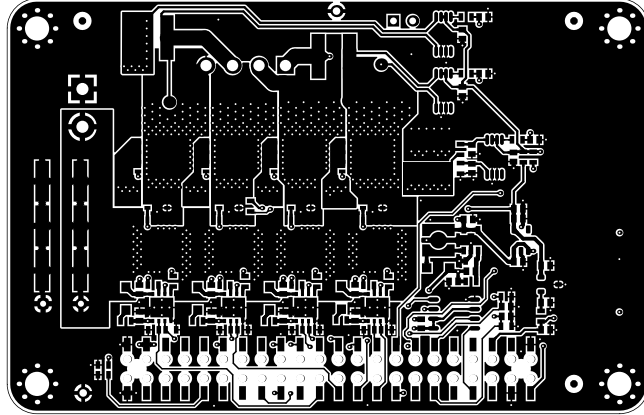
Drill Drawing View (Scale 1:1)



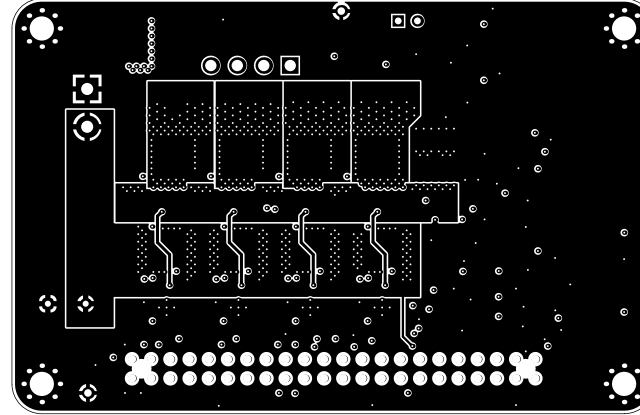
Drill Table

Symbol	Count	Hole Size	Plated	Via / Pad	Hole Tolerance
☆	699	0.25	Plated	Via	None
△	32	0.60	Plated	Via	None
☆	2	0.80	Plated	Pad	None
◇	2	0.90	Plated	Pad	None
◇	2	1.00	Plated	Pad	None
○	44	1.10	Non-Plated	Pad	None
☆	4	1.50	Plated	Pad	None
□	2	1.60	Plated	Pad	None
⊗	2	1.80	Non-Plated	Pad	None
⊕	4	3.20	Plated	Pad	None
793 Total					

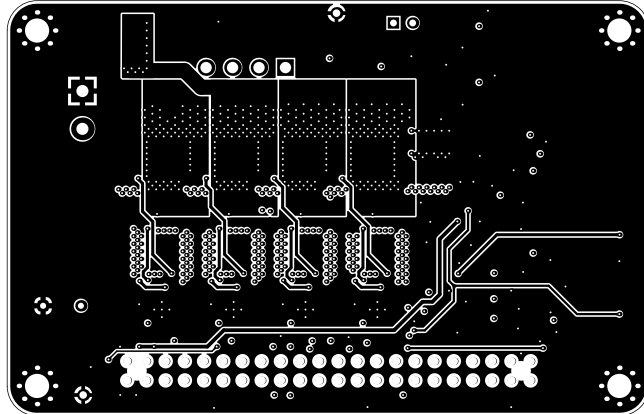
Top Layer (Scale 1:1)



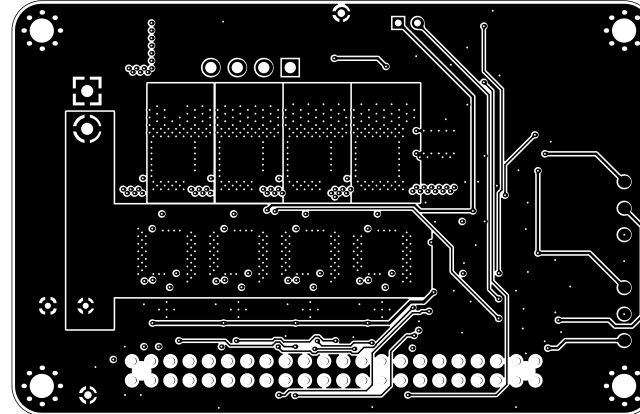
Mid1 (Scale 1:1)



Mid2 (Scale 1:1)

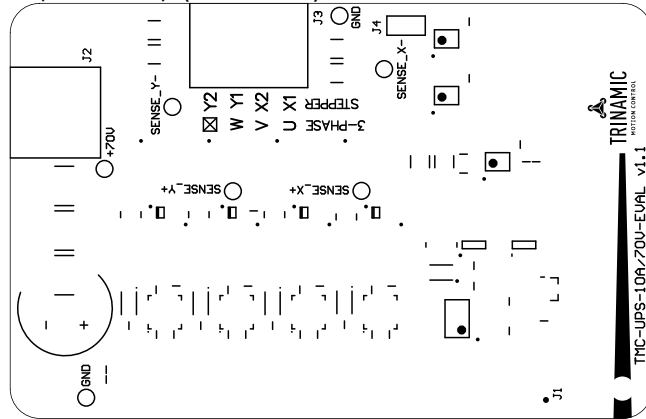


Bottom Layer (Scale 1:1)

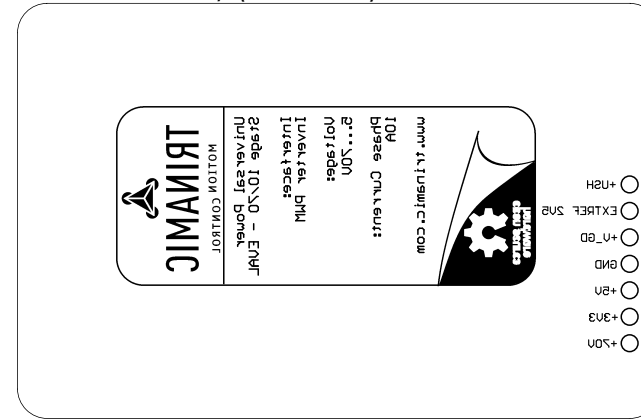


Title		
Fabrication Drawing		
Size	Revision	Project
A4		
Date	18.10.2017 18:36	Sheet 2 of 4
File	UPS 10A EVAL V11-F.PCBDwf	

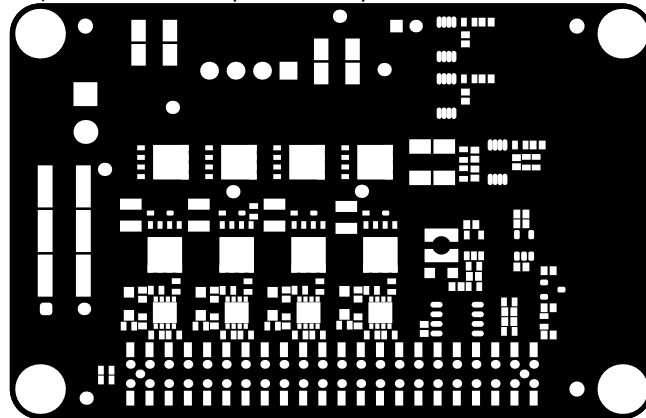
Top Overlay (Scale 1:1)



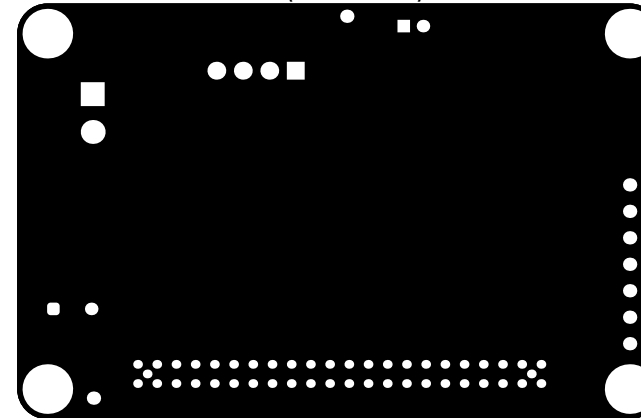
Bottom Overlay (Scale 1:1)



Top Soldermask (Scale 1:1)



Bottom Soldermask (Scale 1:1)



Title		
Size	Revision	Project
A4		
Date	18.10.2017 18:36	Sheet 3 of 4
File	UPS 10A EVAL V11-F.PCBDwf	



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A

B

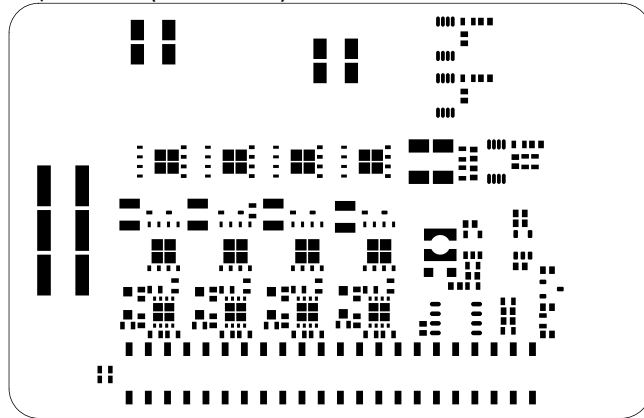
C

D

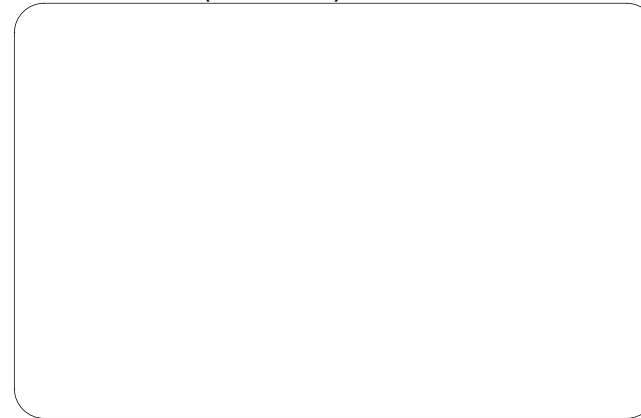
1

1

Top Paste (Scale 1:1)



Bottom Paste (Scale 1:1)



2

2

3

3

4

4

A

B

C

D